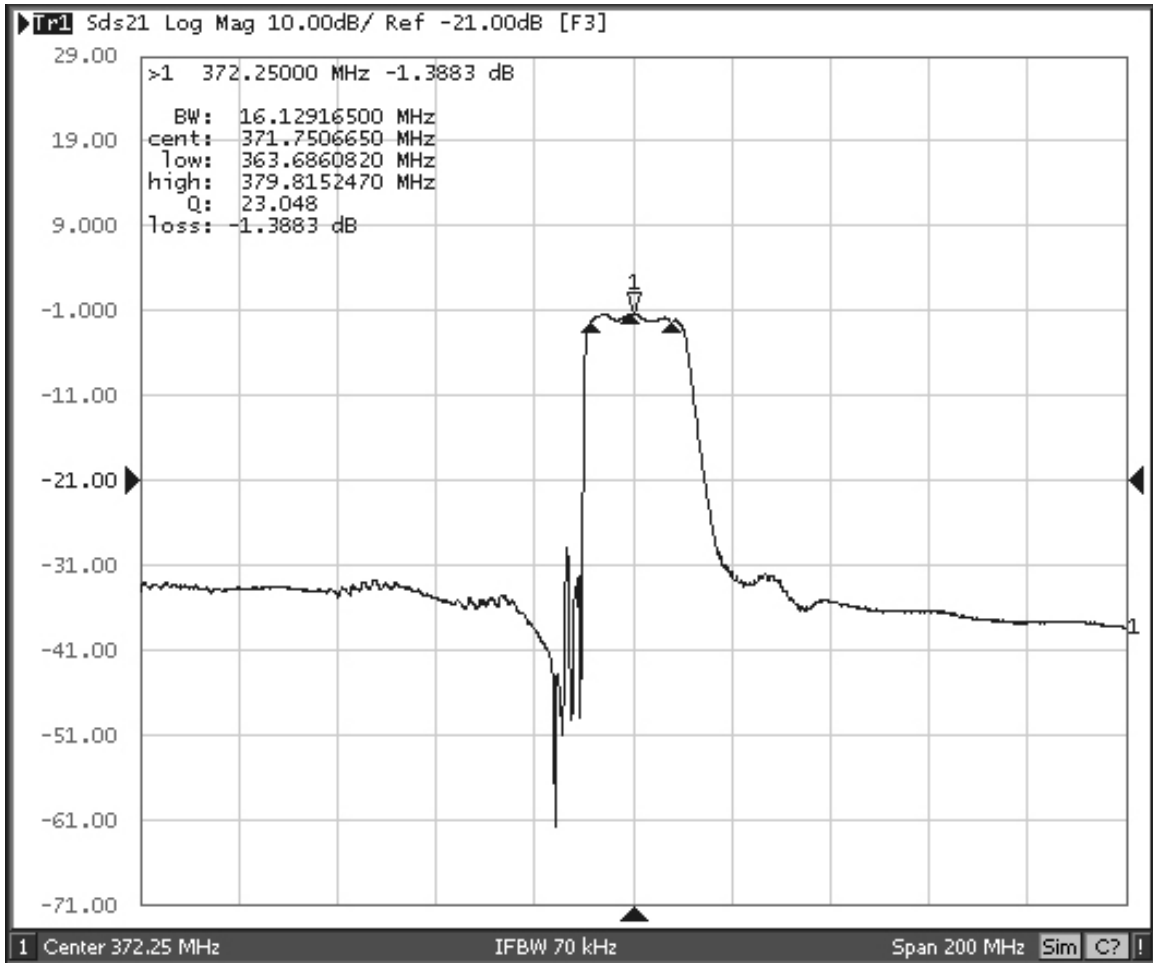




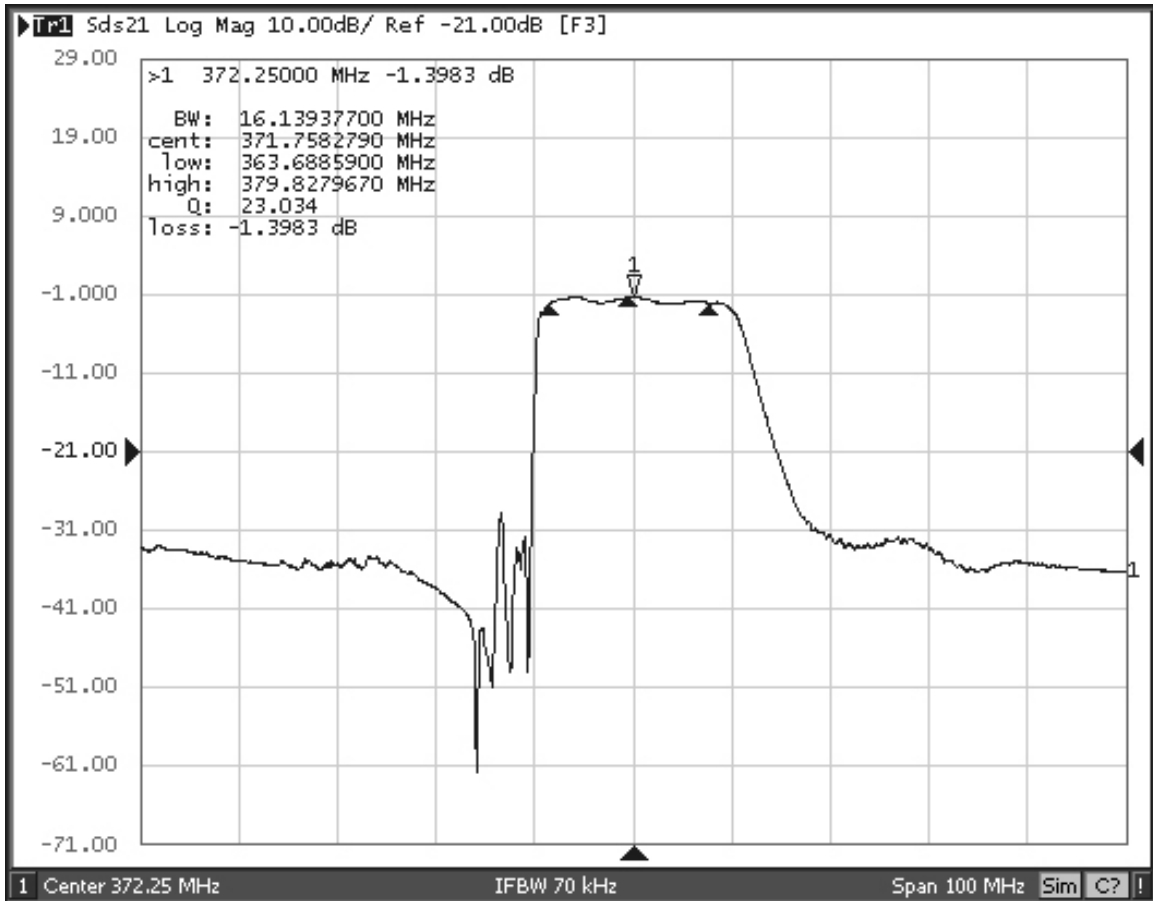




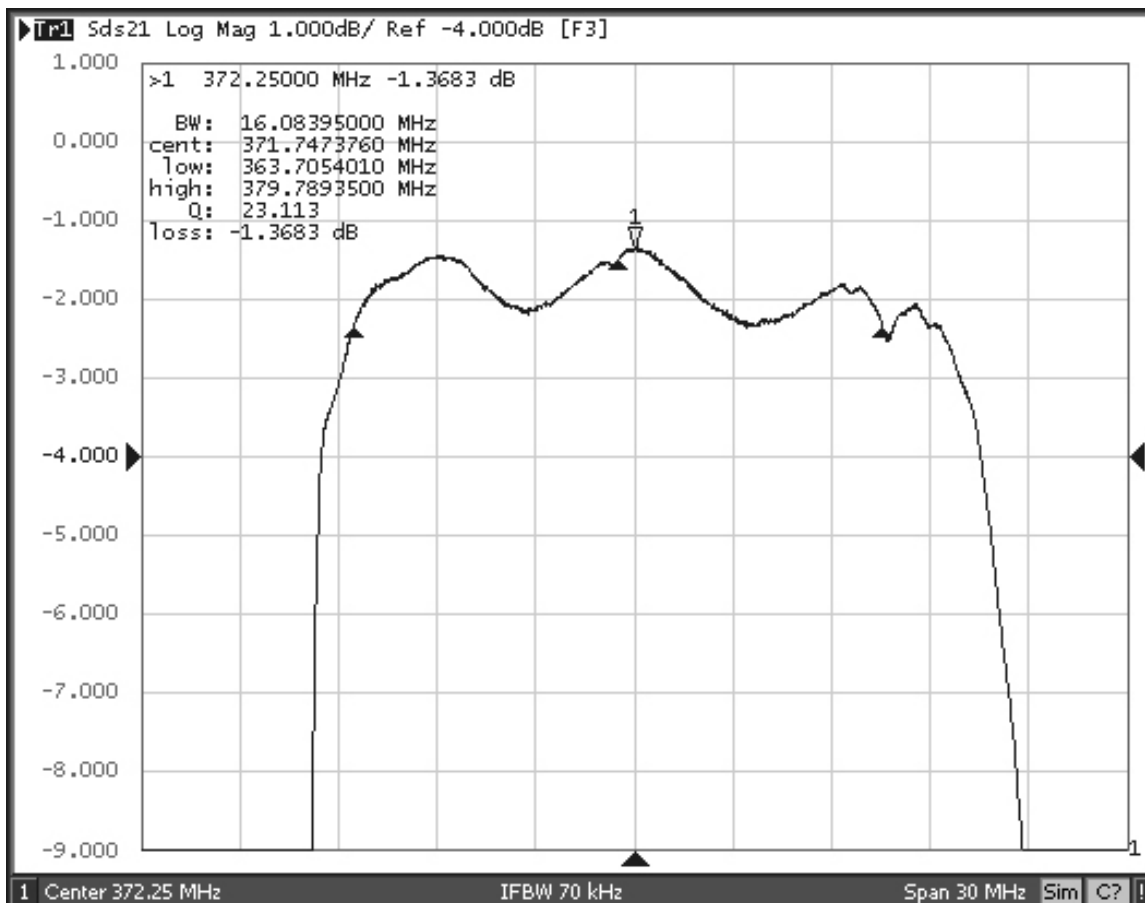
# RF3605D Response, 272.25 to 472.25 MHz



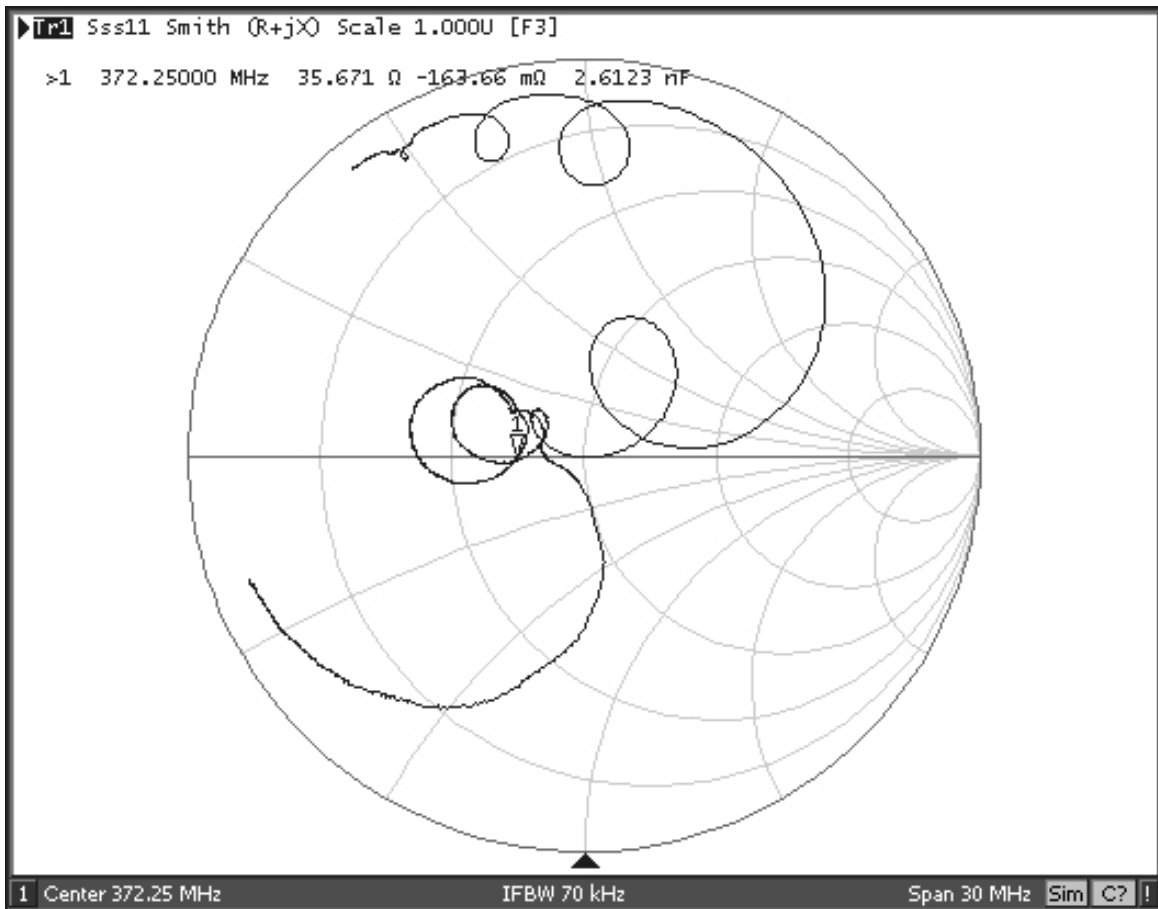
# RF3605D Response, 322.25 to 422.25 MHz



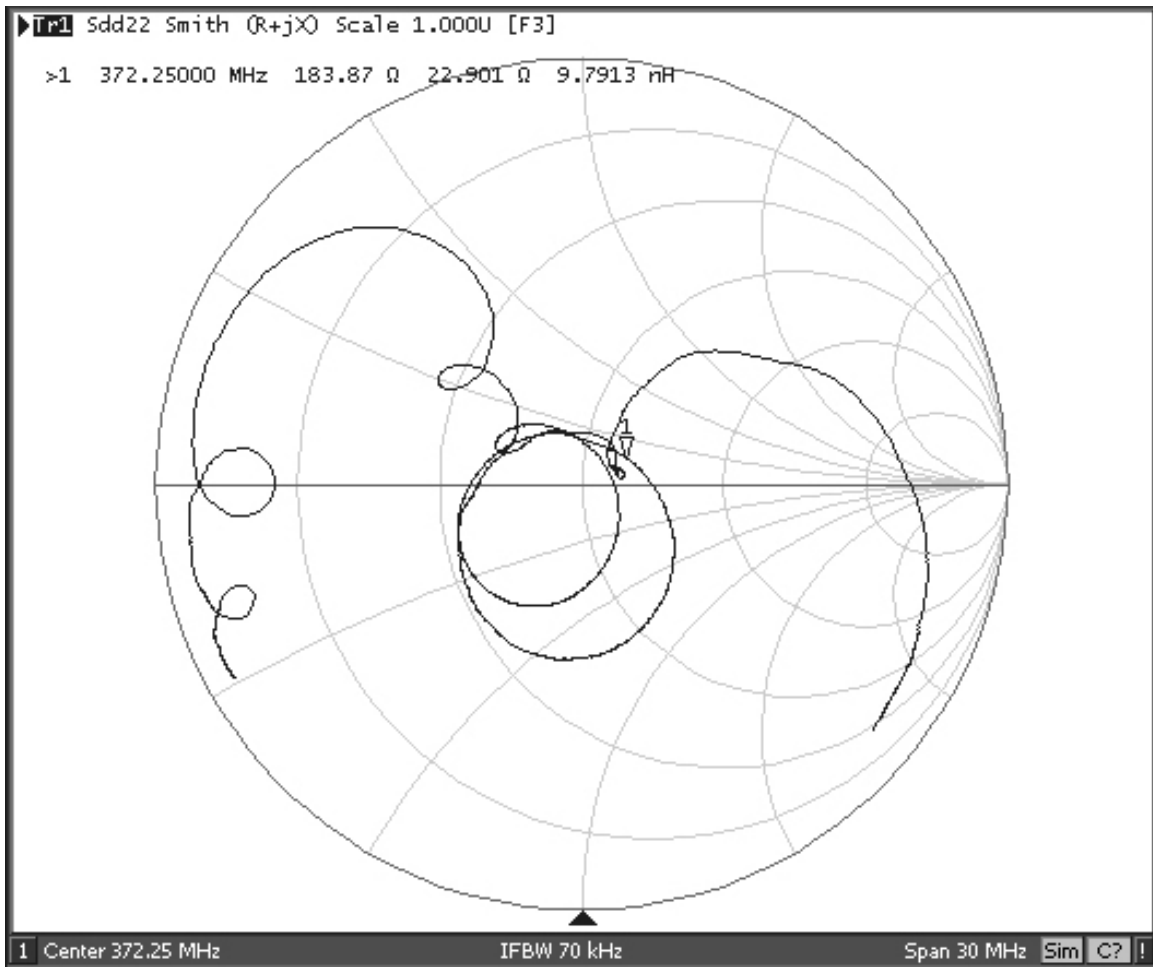
## RF3605D Passband Response



## RF3605D Input Impedance Plot

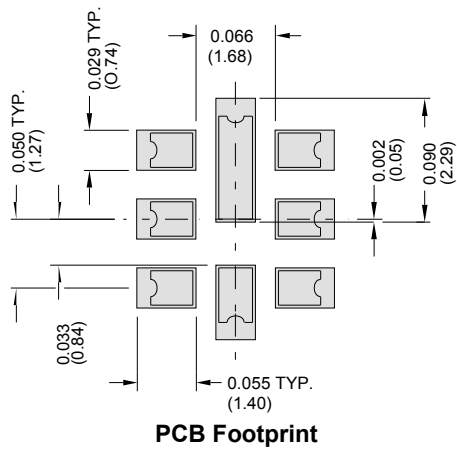


## RF3605D Balanced Output Impedance Plot



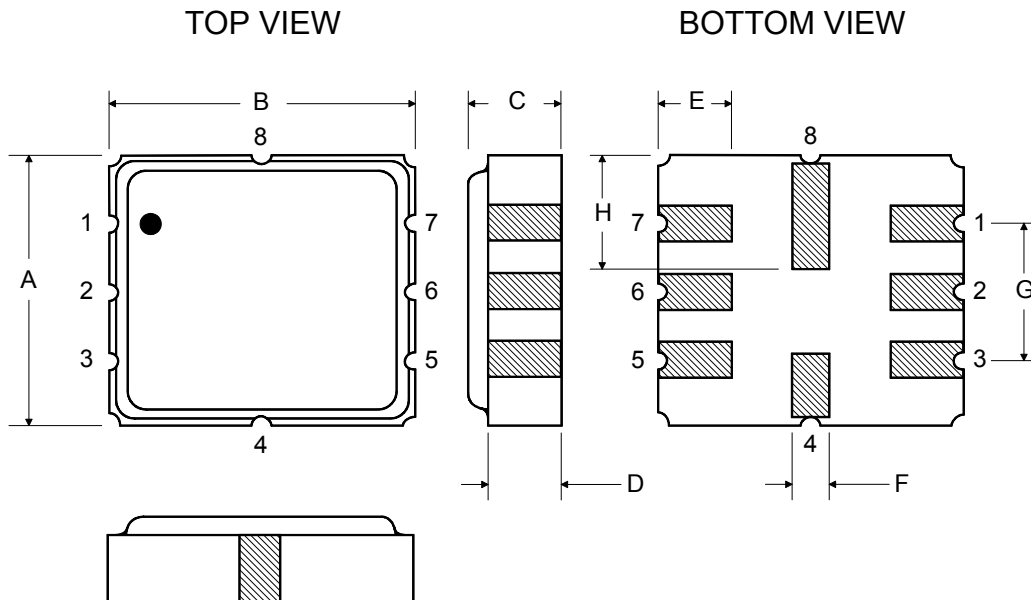


## 8-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint



Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
<b>A</b>	3.6	3.8	4.0	0.142	0.150	0.157
<b>B</b>	3.6	3.8	4.0	0.142	0.150	0.157
<b>C</b>	0.90	1.00	1.1	0.035	0.040	0.043
<b>D</b>	0.80	0.90	1.0	0.031	0.035	0.040
<b>E</b>	0.90	1.00	1.10	0.035	0.040	0.043
<b>F</b>	0.50	0.60	0.70	0.020	0.024	0.028
<b>G</b>	2.39	2.54	2.69	0.090	0.100	0.110
<b>H</b>	1.40	1.75	2.05	0.055	0.069	0.080

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu$ m Gold over 1.27 to 8.89 $\mu$ m Nickel
Lid Plating	2.0 to 3.0 $\mu$ m Nickel
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic
Pb Free	





## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

